



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

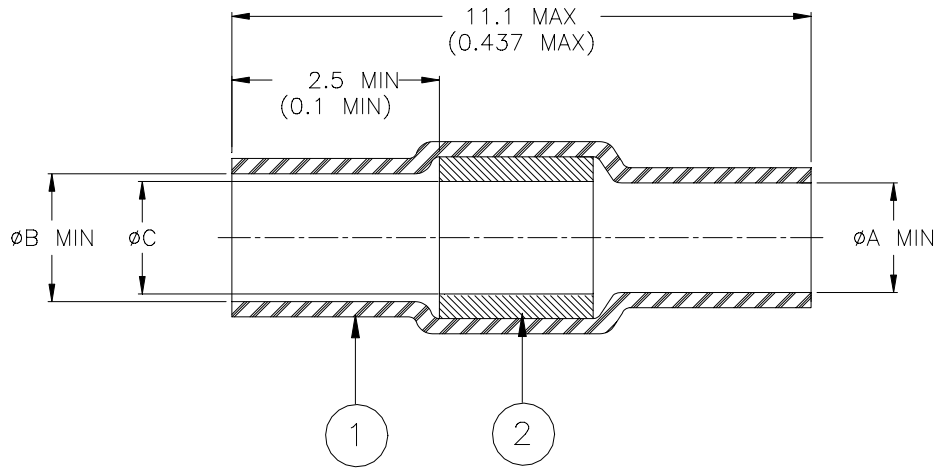
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SPECIFICATION CONTROL DRAWING



Product Name	Product Revision	Product Dimensions		
		ØA ¹ min	ØB ¹ min	ØC ²
D-110-6301	A	1.9 (0.075)	2.65 (0.105)	2.52±0.05 (0.010±0.002)
D-110-6302	A	2.8 (0.110)	3.70 (0.145)	3.15±0.05 (0.124±0.002)
D-110-6303	A	4.6 (0.180)	5.08 (0.200)	5.06±0.1 (0.200±0.004)
D-110-6304	A	6.0 (0.235)	6.35 (0.250)	6.5±0.1 (0.255±0.004)
D-110-6305	A	7.1 (0.280)	7.62 (0.300)	7.6±0.1 (0.300±0.004)
D-110-6306	A	9.0 (0.355)	10.40 (0.410)	10.20±0.08 (0.402±0.003)

1) As received minimum: Insulation diameter for wires entering this end must be less than this value.

2) Solder preform diameter: Combined conductor diameter must be less than this value.

MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.

2. SOLDER PREFORM WITH FLUX:

SOLDER: TYPE Sn63 per ANSI-J-STD-006.

FLUX: TYPE ROL1 per ANSI-J-STD-004.

APPLICATION

1. This part is designed for use in splicing wires rated for at least 125°C, having tin plated conductors.

2. When installed in accordance with Raychem Process Standard RCPS-100-70, parts will meet performance requirements of Raychem Specification RT-1404 for non-sealed splices.

3. Temperature rating: -55°C to +150°C.

4. Pre-tinning wires larger than 20AWG (use Sn63 solder) will decrease installation time and increase usable CMA

Raychem Interconnect <small>a division of tyco ELECTRONICS</small> 300 Constitution Drive Menlo Park, CA 94025, USA		THERMOFIT DEVICES		TITLE: SOLDERSLEEVE DEVICE			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO.: D-110-630X			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Raychem reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DCR NUMBER: D000223		REPLACES: D990841	
DRAWN BY: M. FORONDA	DATE: 20-June-00	PROD. REV. SEE TABLE	DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 1	

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